

L Number	Hits	Search Text	DB	Time stamp
3	10	((decapsulat\$3 or decapp\$3) same ("IC" near package))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 19:33
4	1	(((decapsulat\$3 or decapp\$3) same ("IC" near package))) and @pd<19961029	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 19:33
5	10	(((decapsulat\$3 or decapp\$3) same ("IC" near package))) and circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 19:33
-	1341	(printed near circuit near board or "PCB") same ("IC" near package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 18:16
-	3	((printed near circuit near board or "PCB") same ("IC" near package)) same (decapsulat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 18:15
-	3	((printed near circuit near board or "PCB") same ("IC" near package)) and (decapsulat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 17:47
-	481	((printed near circuit near board or "PCB") same ("IC" near package)) and @pd<19961029	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 17:49
-	171	(((printed near circuit near board or "PCB") same ("IC" near package)) and @pd<19961029) and (test\$3 or inspect\$3 or repair\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 17:50
-	86	(((printed near circuit near board or "PCB") same ("IC" near package)) and @pd<19961029) and (test\$3 or inspect\$3 or repair\$3)) and (remov\$3 near5 epoxy near resin or plastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 17:50
-	8	(((printed near circuit near board or "PCB") same ("IC" near package)) and @pd<19961029) and (test\$3 or inspect\$3 or repair\$3)) and (remov\$3 near5 (epoxy near resin or plastic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 17:56
-	103	((printed near circuit near board or "PCB") same ("IC" near package)) and ((decapsulat\$3 or remov\$3) same (plastic or epoxy near resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 17:59
-	37	(((printed near circuit near board or "PCB") same ("IC" near package)) and ((decapsulat\$3 or remov\$3) same (plastic or epoxy near resin))) and @pd<19961029	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 17:59
-	1	(printed near circuit near board or "PCB") same ("IC" near package)	USOCR	2003/02/13 18:16
-	0	decapsulat\$3 same ("IC" near package)	USOCR	2003/02/13 18:17

-	9	decapsulat\$3 same ("IC" near package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 18:20
-	9	(decapsulat\$3 same ("IC" near package)) and circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/19 19:29
-	3	(decapsulat\$3 same ("IC" near package)) and ((mount\$3 or attach\$3) near5 circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/13 18:21